Analog Devices Welcomes Hittite Microwave Corporation
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ST89 (E) – 4 LEAD PLASTIC SOT89 PACKAGE

ST89 (E) Package Outline Drawing

Package Information

<table>
<thead>
<tr>
<th>Part Number Suffix</th>
<th>Package Body Material</th>
<th>Lead Finish</th>
<th>MSL Rating</th>
<th>Package Marking[^3][^4]</th>
</tr>
</thead>
<tbody>
<tr>
<td>ST89</td>
<td>RoHS Compliant Mold Compound</td>
<td>Sn/Pb Solder</td>
<td>MSL1[^1]</td>
<td>HNNN XXXX</td>
</tr>
<tr>
<td>ST89E</td>
<td>RoHS Compliant Mold Compound</td>
<td>100% matte Sn</td>
<td>MSL1[^2]</td>
<td>HNNN XXXX</td>
</tr>
</tbody>
</table>

[^1]: Max peak reflow temperature of 235 °C
[^2]: Max peak reflow temperature of 260 °C
[^3]: 4-Digit lot number XXXX
[^4]: 3-Digit part number NNN

NOTES:
1. PACKAGE BODY MATERIAL:
   MOLDING COMPOUND MP-180S OR EQUIVALENT.
2. LEAD MATERIAL: Cu w/ Ag SPOT PLATING.
3. LEAD PLATING: 100% MATTE TIN.
4. DIMENSIONS ARE IN INCHES [MILLIMETERS]
   △ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
   △ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
7. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.
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Suggested ST89 (E) PCB Land Pattern

NOTES:
1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.